



Customer Information Notification

202104025I : NXP Final Test Site Relocation Initiative: ATTJ to ATTJ

Building 2 (ATTJ-B2) - Phase 2

Note: This notice is NXP Company
Proprietary.

Issue Date: Apr 20, 2021 **Effective date:** May 21, 2021

Change Category

- | | | | | |
|--|--|--|--|---|
| <input type="checkbox"/> Wafer
Fab
Process | <input type="checkbox"/> Assembly
Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Test
Process | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer
Fab
Materials | <input type="checkbox"/> Assembly
Materials | <input type="checkbox"/> Mechanical
Specification | <input type="checkbox"/> Test
Equipment | <input type="checkbox"/> Errata |
| <input type="checkbox"/> Wafer
Fab
Location | <input type="checkbox"/> Assembly
Location | <input type="checkbox"/> Packing/Shipping/Labeling | <input checked="" type="checkbox"/> Test
Location | <input type="checkbox"/> Electrical
spec./Test
coverage |
| <input type="checkbox"/> Firmware | <input type="checkbox"/> Other | | | |

PCN Overview

Description

NXP Semiconductors announces the ATTJ Final Test Site Relocation Initiative from the current NXP ATTJ, Tianjin, China test site to local, nearby (2.5km away) ATTJ-B2 test site, creating a consolidated ATTJ Test Center of Excellence. The associated Test Backend Shipping / Packing Operations relocate to the ATTJ-B2 site as well.

This NXP Initiative is a phased / ramped relocation activity, until all Final Test platform types have been relocated to the ATTJ-B2.

This major, strategic NXP initiative ensures future scalability of NXP ATTJ backend manufacturing sites, ATTJ main factory and new ATTJ-B2, to support current and future business. The current ATTJ main factory manufacturing floor space is fully utilized. Final Test and Test Backend Shipping / Packing Operations must be migrated to the new ATTJ-B2 Test Center of Excellence, while the existing ATTJ main factory will be exclusive for assembly and other non-Final Test operations. This initiative allows growth opportunities for both ATTJ manufacturing buildings for customer supply assurance.

The ATTJ-B2 is located 2.5 km Southeast from the current ATTJ main factory site, and adheres to the same ATTJ criteria: 100k clean room rating, temperature / humidity / ESD controls, and quality accreditations.

All current ATTJ main factory Final Test equipment (hardware / software), test flows, test programs, policies, procedures, and personnel will be relocated to the new ATTJ-B2. Absolutely no impact to product form, fit, function or reliability.

Please see the attached documents for additional details, including Qualification Results.

Reason

Qualification of NXP ATTJ, Tianjin, China new ATTJ-B2 is a new NXP strategic initiative to create a consolidated ATTJ Test Center of Excellence for Final Test Site and associated Test Backend Shipping / Packing Operations for current and future customer supply assurance.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Existing inventory will be shipped until depleted

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name Vivian Sun

Position Product & Test Engineering
Manager

e-mail
address vivian.sun@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

NXP Semiconductors N.V. (NASDAQ: NXPI) provides High Performance Mixed Signal and Standard Product solutions that leverage its leading RF, Analog, Power Management, Interface, Security and Digital Processing expertise. These innovations are used in a wide range of automotive, identification, wireless infrastructure, lighting, industrial, mobile, consumer and computing applications.

NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

© 2006- 2021 NXP Semiconductors. All rights reserved.